

### DMP4025LK3Q

#### **40V P-CHANNEL ENHANCEMENT MODE MOSFET**

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C (Note 6)
-40V	$25m\Omega$ @ $V_{GS} = -10V$	-8.6A
- <del>4</del> 0 v	$45 \text{m}\Omega$ @ $V_{GS} = -4.5V$	-7.0A

### **Description**

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

### **Applications**

- Motor Control
- Backlighting
- DC-DC Converters
- Printer Equipment

### **Features**

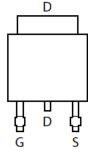
- Low On-Resistance
- · Fast Switching Speed
- Low Input/Output Leakage
- Lead-Free Finish; RoHS compliant (Note 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Available (Note 4)

### **Mechanical Data**

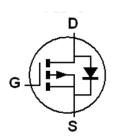
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See diagram below
- Terminals: Finish Matte Tin annealed over Copper lead frame.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.315 grams (approximate)



Top View



Top View Pin Out



Device symbol

### Ordering Information (Note 4 & 5)

Part Number	Compliance	Case	Packaging
DMP4025LK3Q-13	Automotive	TO252	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product\_grade\_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## Marking Information



Office Manufacturer's Marking
P4025L = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 10 = 2010)
WW = Week (01 - 53)



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage	Drain-Source Voltage			-40	
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
		(Notes 7)		-8.6	
Continuous Drain Current	V <sub>GS</sub> = -10V	T <sub>A</sub> = +70°C (Notes 7)	I <sub>D</sub>	-6.9	
		(Notes 6)		-6.7	
Pulsed Drain Current	V <sub>GS</sub> = -10V	(Notes 8)	I <sub>DM</sub>	-35	Α
Continuous Source Current (Body diode)		(Notes 8)	I <sub>S</sub>	-8.6	]
Pulsed Source Current (Body diode) (N		(Notes 8)	I <sub>SM</sub>	-35	

## Thermal Characteristics (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Power Dissipation	(Notes 6)	D	1.7	10/
Power Dissipation	(Notes 7)	P <sub>D</sub>	2.78	W
The control Designation of Ameliana	(Notes 6)	Б	74	00.004
Thermal Resistance, Junction to Ambient	(Notes 7)	$R_{\theta JA}$	45	
Thermal Resistance, Junction to Case	(Notes 7)	R <sub>0JC</sub>	7.1	°C/W
Thermal Resistance, Junction to Lead (Notes 9)		R <sub>0JL</sub>	1.43	
Operating and Storage Temperature Range	T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C	

Notes:

- 6. For a device surface mounted on minimum recommended FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 7. Same as note (5), except the device is surface mounted on 25mm X 25mm X 1.6mm FR4 PCB.

  8. Repetitive rating on 25mm X 25mm FR4 PCB, D=0.02, pulse width 300µs pulse width by maximum junction temperature.

  9. Thermal resistance from junction to solder-point (at the end of the drain lead).



### Thermal Characteristics

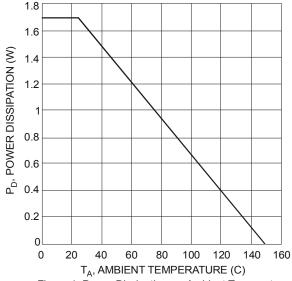
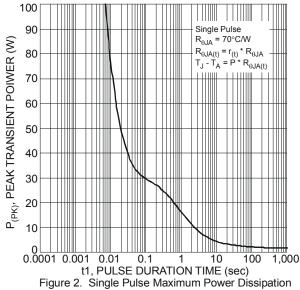
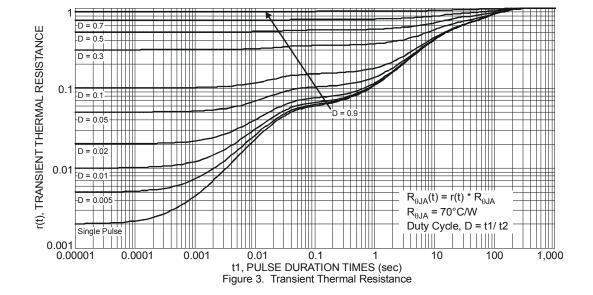


Figure 1. Power Dissipation vs. Ambient Temperature







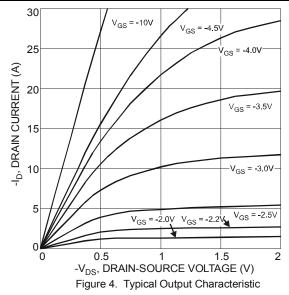
## Electrical Characteristics (@TA = +25°C unless otherwise specified.)

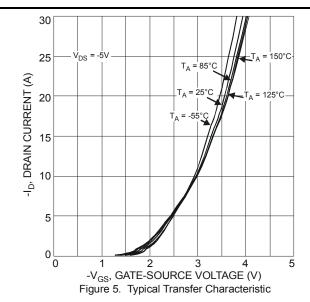
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-40	_	_	V	$I_D = -250 \mu A, V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		_	-1	μA	V <sub>DS</sub> = -40V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>		_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	$V_{GS(th)}$	-0.8	-1.3	-1.8	V	$I_D = -250 \mu A, V_{DS} = V_{GS}$	
Static Drain Source On Desigtance (Note 10)	0		18	25	mΩ	$V_{GS} = -10V, I_D = -3A$	
Static Drain-Source On-Resistance (Note 10)	R <sub>DS</sub> (ON)	_	30	45	11122	$V_{GS} = -4.5V$ , $I_{D} = -3A$	
Forward Transconductance (Notes 10 & 11)	9 <sub>fs</sub>		16.6	_	S	$V_{DS} = -5V, I_{D} = -3A$	
Diode Forward Voltage (Note 10)	$V_{SD}$	_	-0.7	-1	V	I <sub>S</sub> = -1A, V <sub>GS</sub> = 0V	
DYNAMIC CHARACTERISTICS (Note 11)							
Input Capacitance	C <sub>iss</sub>		1643	_			
Output Capacitance	Coss		179	_	pF	$V_{DS} = -20V, V_{GS} = 0V$ f = 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		128	_		1 - 1101112	
Gate Resistance	Rg	_	6.43	_	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz	
Total Gate Charge (Note 12)	Qg		14	_		V <sub>GS</sub> = -4.5V	
Total Gate Charge (Note 12)	Qg	_	33.7	_	nC	V <sub>DS</sub> = -20V	
Gate-Source Charge (Note 12)	Qgs	_	5.5	_	IIC	$V_{GS} = -10V$ $I_D = -3A$	
Gate-Drain Charge (Note 12)	Q <sub>gd</sub>	_	7.3	_			
Turn-On Delay Time (Note 12)	t <sub>D(on)</sub>	_	6.9	—			
Turn-On Rise Time (Note 12)	t <sub>r</sub>		14.7	_		V <sub>DD</sub> = -20V, V <sub>GS</sub> = -10V	
Turn-Off Delay Time (Note 12)	t <sub>D(off)</sub>		53.7	_	ns	I <sub>D</sub> = -3A	
Turn-Off Fall Time (Note 12)	t <sub>f</sub>		30.9	_			

Notes:

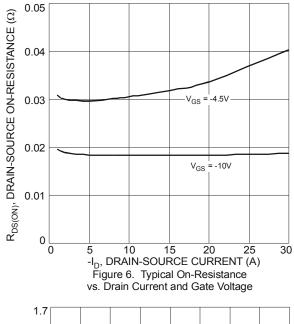
- 10. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s; duty cycle  $\leq$  2%. 11. For design aid only, not subject to production testing. 12. Switching characteristics are independent of operating junction temperatures.

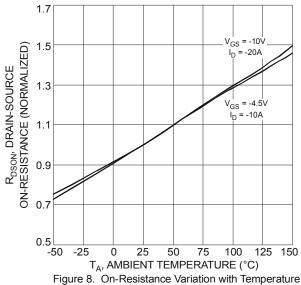
# **Typical Characteristics**











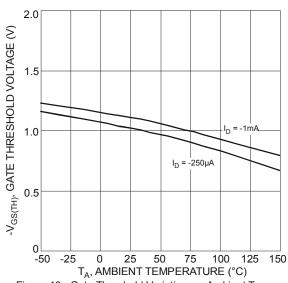
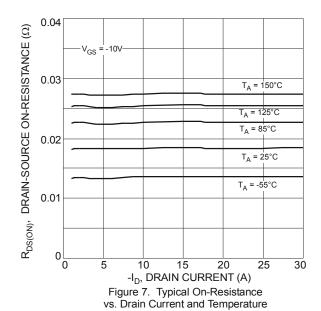


Figure 10. Gate Threshold Variation vs. Ambient Temperature



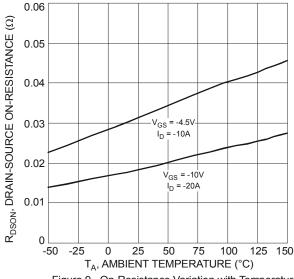


Figure 9. On-Resistance Variation with Temperature

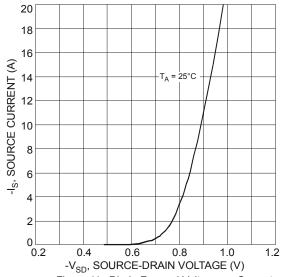
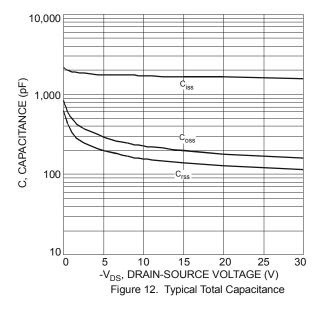
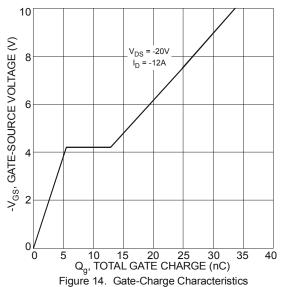
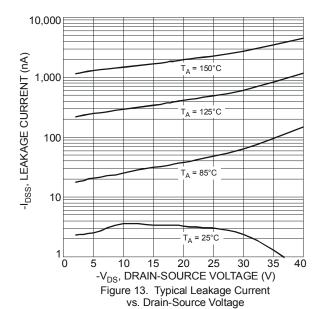


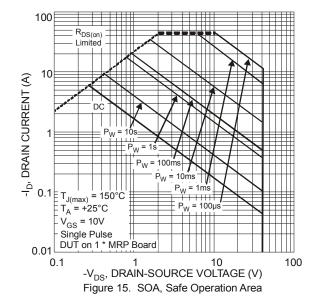
Figure 11. Diode Forward Voltage vs. Current







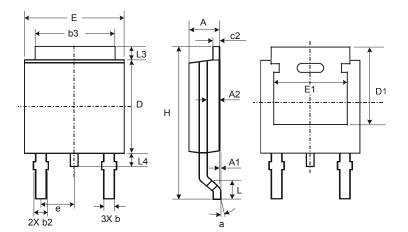






# **Package Outline Dimensions**

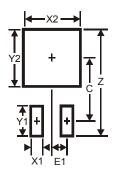
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



TO252					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
<b>A1</b>	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
c2	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	_	_		
е	_	_	2.286		
Е	6.45	6.70	6.58		
E1	4.32	_	_		
Н	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	_		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
Z	11.6		
X1	1.5		
X2	7.0		
Y1	2.5		
Y2	7.0		
С	6.9		
F1	23		



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